

TIL305 5 × 7 ALPHANUMERIC DISPLAY

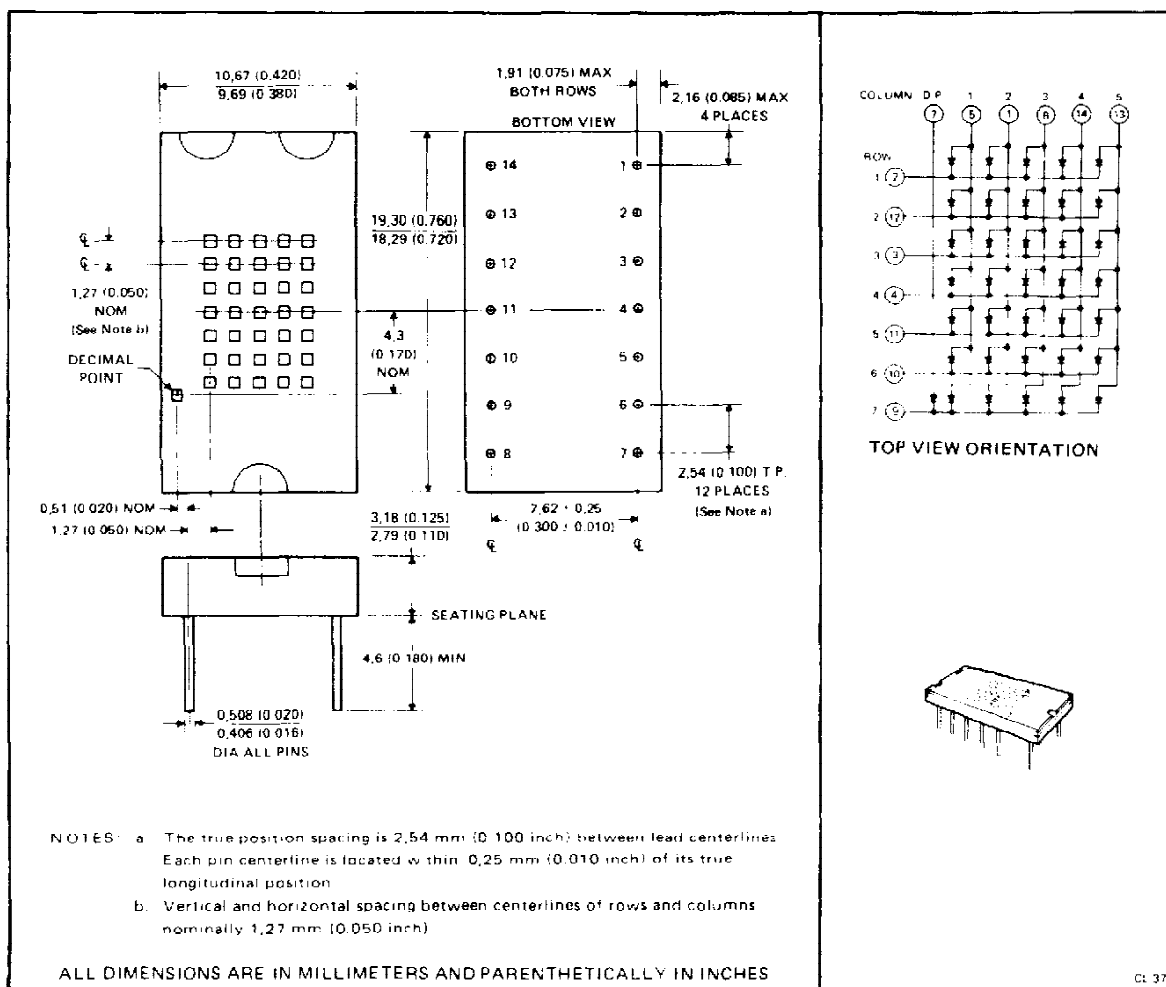
SODS002 D1033, MAY 1971 - REVISED MARCH 1983

SOLID-STATE DISPLAY WITH RED TRANSPARENT PLASTIC ENCAPSULATION

- 7,62-mm (0.300-inch) Character Height
- High Luminous Intensity
- Low Power Requirements
- Wide Viewing Angle
- 5 X 7 Array with X-Y Select and Decimal
- Compatible with USASCII and EBCDIC Codes

mechanical data

This assembly consists of a display chip mounted on a printed circuit board with a red molded plastic body. Multiple displays may be mounted on 11,43-mm (0.450-inch) centers.



PRODUCTION DATA documents contain information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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TIL305

5 × 7 ALPHANUMERIC DISPLAY

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Reverse Voltage at 25°C Free-Air Temperature	3 V
Peak Forward Current, Each Diode	100 mA
Average Forward Current (see Note 1):	
Each Diode	10 mA
Total	200 mA
Operating Free-Air Temperature Range	0° to 70°C
Storage Temperature Range	−25°C to 85°C

operating characteristics of each diode at 25°C free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_V Luminous Intensity (see Note 2)	$I_F = 10\text{ mA}$	40	110		μcd
λ_p Wavelength at Peak Emission			660		nm
Δ Spectral Bandwidth			20		nm
V_F Static Forward Voltage		1.5	1.65	2	V
α_{VF} Average Temperature Coefficient of Static Forward Voltage	$I_F = 10\text{ mA}$, $T_A = 0^\circ\text{C to } 70^\circ\text{C}$	−1.4			mV/°C
I_R Static Reverse Current	$V_R = 3\text{ V}$		10		μA
C Anode-to-Cathode Capacitance	$V_R = 0$, $f = 1\text{ MHz}$		80		pF

NOTES: 1. This average value applies for any 1 ms period.

2. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (International Commission on Illumination) eye response curve.

TYPICAL CHARACTERISTICS

RELATIVE LUMINOUS INTENSITY
VS
FREE-AIR TEMPERATURE

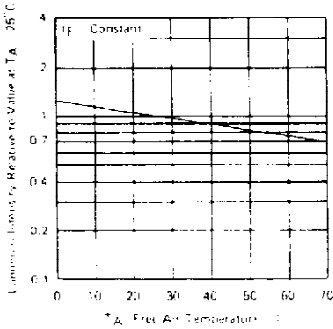


FIGURE 1

RELATIVE LUMINOUS INTENSITY
VS
FORWARD CURRENT

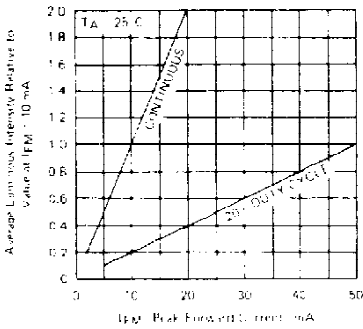


FIGURE 2

FORWARD CONDUCTION
CHARACTERISTICS

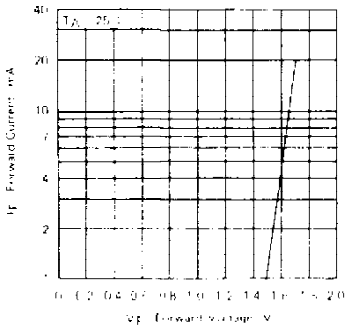


FIGURE 3

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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TIL305	OBSOLETE			14		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

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⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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